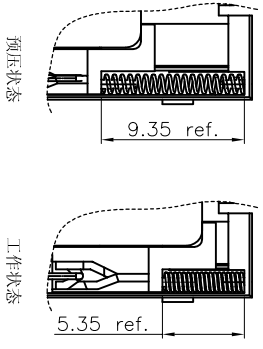
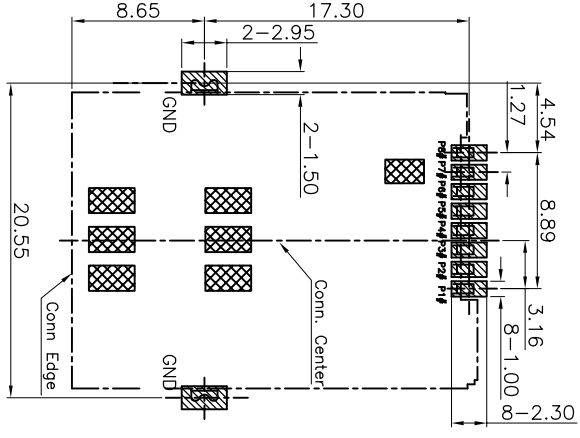
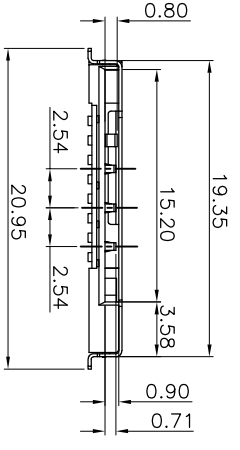
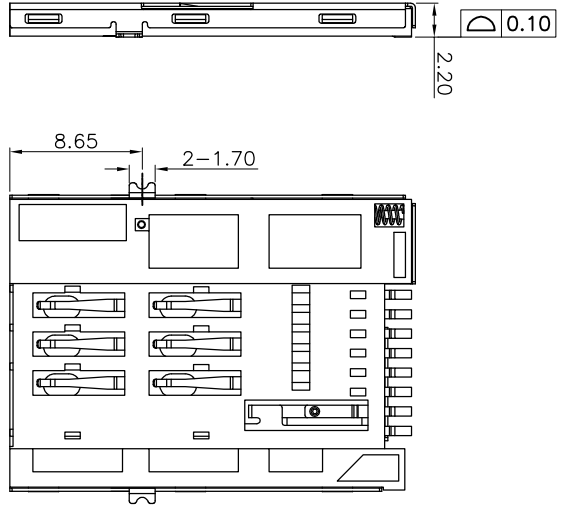
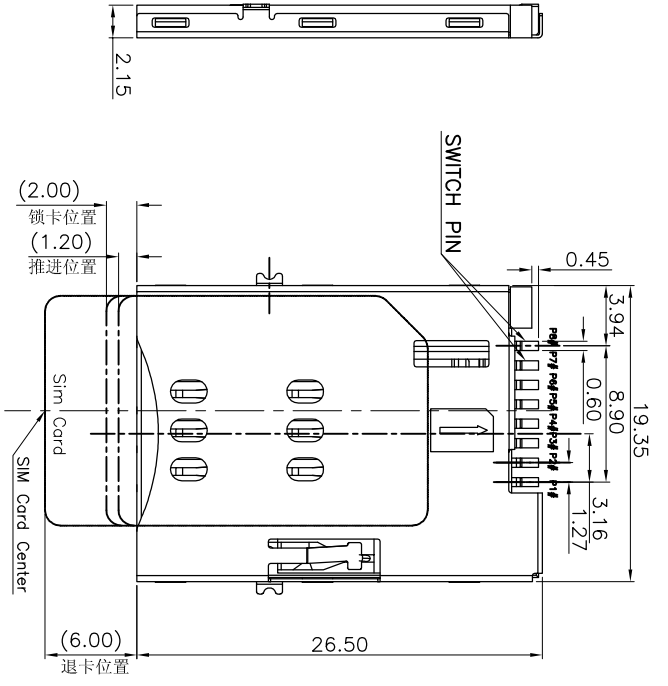
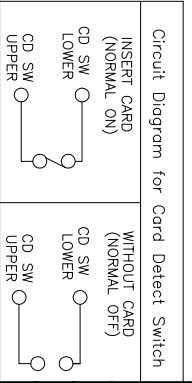


REV.	EGN.NO.	MODIFY CONTENT	DATE
A		NEW	2013/11/02

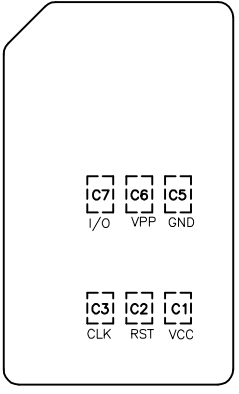


PIN NO.	DESCRIPTION
P1#	C1:VCC
P2#	C5:GND
P3#	C2:RST
P4#	C6:VPP
P5#	C3:CLK
P6#	C7:I/O
P7#	POL
P8#	DET



RECOMMENDED PCB LAYOUT(TOP VIEW)
GENERAL TOLERANCES:±0.05

SOLDER AREA
 NONE CIRCUIT DIAGRAM AREA



NOTES:
 1) MATERIAL:
 HOUSING: LCP UL 94V-0
 CONTACT: C5210R-H,T=0.15
 SHELL: SUS201,T=0.15
 MYLAR: POLYESTER
 2) FINISH:
 CONTACT: GOLD FLASH PLATED ON CONTACT AREA;
 GOLD FLASH PLATING ON SOLDER TAILS, WITH
 ENTIRE CONTACT UNDERPLATED
 50u"Min,NICKEL
 SHELL: 50u"Min, NICKEL UNDERPLATED OVERALL,
 GOLD FLASH PLATED ON SOLDER TAILS
 3) INFRARED REFLOW SOLDERING: 10sec. Min. at 260±10

GENERAL TOLERANCE	DWG NO.	JYS A1102-003	APPD:	spring	Scale	1:1
X±0.25	X:±5'		CHKD:		UNIT	mm
X±0.20	X:±2'		DR:			
.XX±0.15	.XX±1'		Date	2013/11/02		
.XXX±0.08	.xxx±0.5'					
SHEET 1/2						

杰宇森电子有限公司
 JIE YU SEN ELECTRONIC CO., LTD.

图一

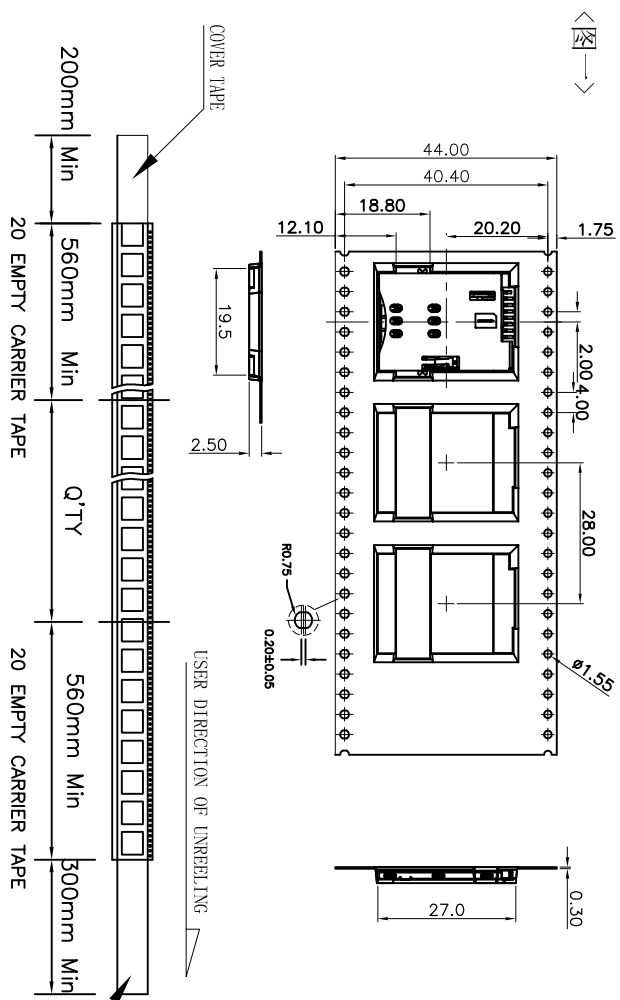
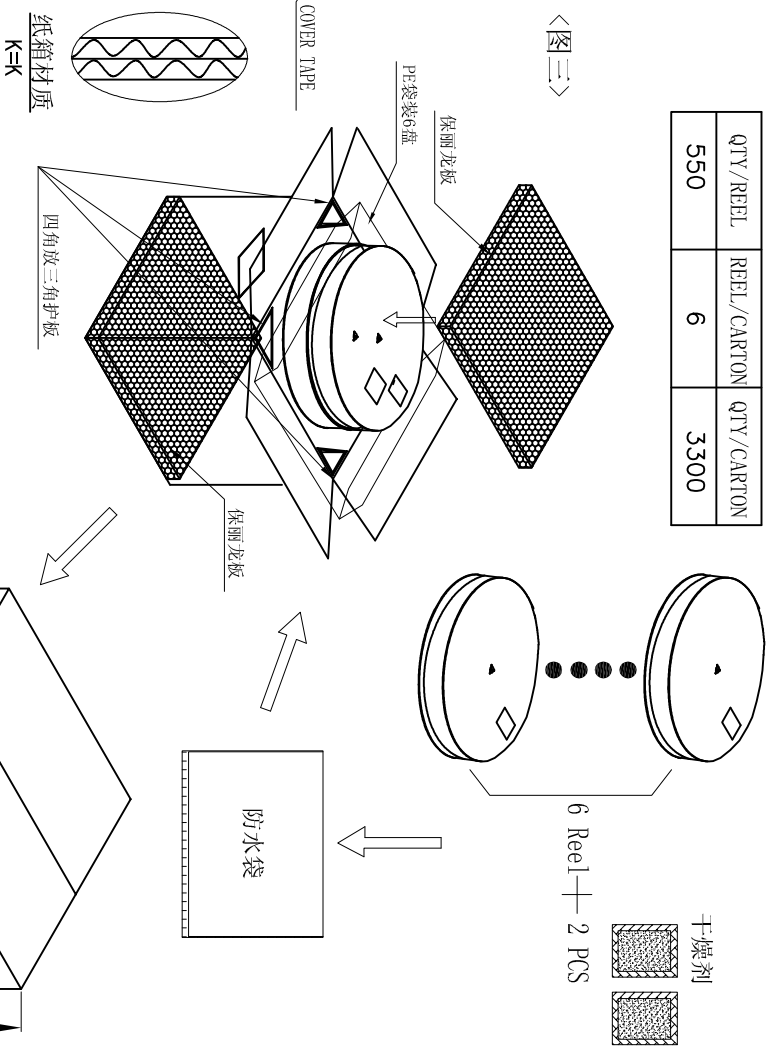


TABLE 1 > PACKAGING QUANTITY

QTY/REEL	REEL/CARTON	QTY/CARTON
550	6	3300

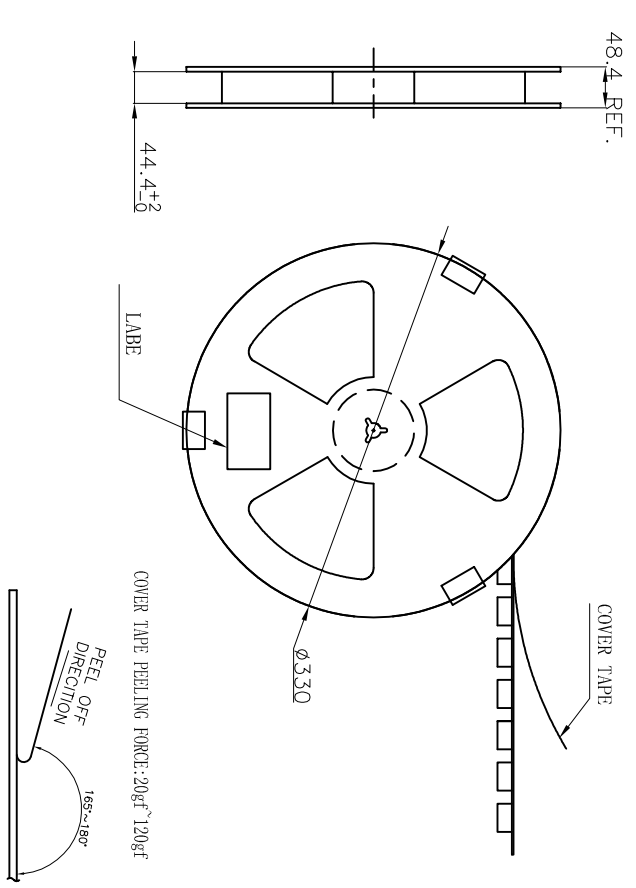
图三



备注:

1. 依图一所示放置产品于Carrier tape中, 每穴放置1PCS产品, Carrier tape卷绕时, 前端和尾端各需预留20PCS空格.
2. Cover tape覆盖Carrier tape前端需超出200mmMIN, 后端需留出300mmMIN, 两端都以美文胶贴固.
3. 包装机包好后, 在Reel的不等分点贴上胶带, 以防止REEL张开, 每Reel贴1PCS标签, 如图二所示
4. 包装数量见如TABLE 1所示
5. 包装成箱见如图三所示
6. 封箱, 在封好的纸箱侧面中间位置贴上出货标签.

图二



GENERAL TOLERANCE	图号	YJSA1512-001	设计	比例	1:1
X±0.45	X:±5'	SIM CARD PUSH 6+2PIN	审核	单位	mm
X±0.35	X:±2'	2.2H (侦测一体) 包装图	核准	视角	AO
.XX±0.25	.XX'±1'	料号	日期	版本	AO
.XX±0.15	.XX'±0.5'	JYS-SIM220-162	2013/11/02		
页号	2/2				